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Reliability Aspects of Lead-Free Solder Alloys Used in Electronics

Guest Editor:

Dr. Bálint Medgyes
Budapest University of Technology and Economics, Budapest, Hungary

Deadline for manuscript submissions:
closed (30 June 2021)

Message from the Guest Editor

Dear Colleagues,

Lead-free solder alloys are used in numerous electronic devices and systems and becoming more important in our everyday lives.

In many fields, electronic devices need to operate in harsh environments, so not only the quality but the long-term reliability of the applied alloys is also critical. There is a strong need to investigate the temperature- and humidity-induced failure mechanisms in these alloys, such as electrochemical migration, corrosion, intermetallic formation, and microstructural changes, and their effects on alloy properties, which affect the life-time of electronic devices. It is also necessary to examine the possible surface-preservation methods of the applied material systems against the most frequent failure mechanisms (e.g., oxidation, dendrite, and whisker growth).

This Special Issue is dedicated to disseminating the recent topics and the latest results on reliability in electronics. We invite colleagues to contribute to this Special Issue with works addressing the aforementioned topics and following keywords in the form of full papers, short communications, and reviews.

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Department of Materials Science and Engineering, College of Engineering & Applied Science, University of Wisconsin-Milwaukee, 3200 N. Cramer Street, Milwaukee, WI 53211, USA

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Beijing Advanced Innovation Center of Materials Genome Engineering, State Key Laboratory for Advanced Metals and Materials, University of Science and Technology Beijing, 30 Xueyuan Road, Beijing 100083, China

Message from the Editorial Board

Metallic materials play a vital role in the economic life of modern societies; contributions are sought on fresh developments that enhance our understanding of the fundamental aspects related to the relationships between processing, properties and microstructure – disciplines in the metallurgical field ranging from processing, mechanical behavior, phase transitions and microstructural evolution, nanostructures, as well as unique metallic properties – inspire general and scholarly interest among the scientific community.

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Contact Us

Metals Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
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metals@mdpi.com
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